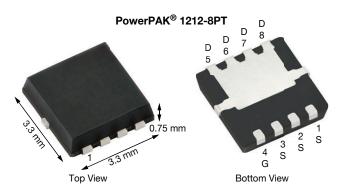
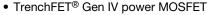
Vishay Siliconix

N-Channel 40 V (D-S) MOSFET



PRODUCT SUMMARY			
V _{DS} (V)	40		
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0074		
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0096		
Q _g typ. (nC)	14.2		
I _D (A)	65		
Configuration	Single		

FEATURES





 \bullet Very low Q_g and Q_{oss} reduce power loss and improve efficiency

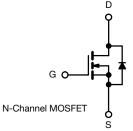
COMPLIANT HALOGEN **FREE**

 Optimized Q_g, Q_{gd}, and Q_{gd}/Q_{gs} ratio reduces switching related power loss

- 100 % R_g and UIS tested
- · Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- · Synchronous rectification
- · Synchronous buck converter
- High power density DC/DC
- · Load switching



ORDERING INFORMATION			
Package	PowerPAK 1212-8PT		
Lead (Pb)-free and halogen-free	Si7116BDN-T1-GE3		

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	40	V	
Gate-source voltage		V_{GS}	± 20	v	
	T _C = 25 °C		65		
Continuous drain current (T _J = 150 °C)	T _C = 70 °C	1 .	52		
	T _A = 25 °C	l _D	18.4 b, c		
	T _A = 70 °C	1	14.7 ^{b, c}	^	
Pulsed drain current (t = 100 μs)		I _{DM}	100	A	
Continuous source-drain diode current	T _C = 25 °C		57		
	T _A = 25 °C	- I _S	4.5 ^{b, c}		
Single pulse avalanche current	1 0.1 ml l	I _{AS}	30		
Single pulse avalanche energy	L = 0.1 mH	E _{AS}	45	mJ	
Maximum power dissipation	T _C = 25 °C		62.5		
	T _C = 70 °C		40	w	
	T _A = 25 °C	P _D	5 b, c	VV	
	T _A = 70 °C	1	3.2 ^{b, c}		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) c			260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b	t ≤ 10 s	R _{thJA}	20	25	°C/W	
Maximum junction-to-case (drain)	Steady state	R _{thJC}	1.4	2.0]	

Notes

- $T_C = 25$ °C
- b. Surface mounted on 1" x 1" FR4 board

Rework conditions: manual soldering with a soldering iron is not recommended for leadless components Maximum under steady state conditions is 60 °C/W

See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

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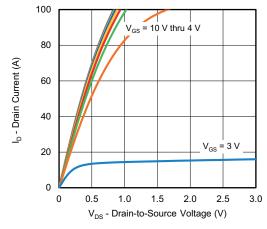
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static			•			
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	1 050 A	-	52	-	mV/°C
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	1.1	-	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.5	-	2.5	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Zero gate voltage drain current		$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	
	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	μA
On-state drain current a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30	-	-	Α
.		V _{GS} = 10 V, I _D = 16 A	-	0.0060	0.0074	Ω
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$	-	0.0075	0.0096	
Forward transconductance a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 25 \text{ A}$	-	80	-	S
Dynamic ^b		-			L	
Input capacitance	C _{iss}		-	1915	-	pF
Output capacitance	C _{oss}		-	230	-	
Reverse transfer capacitance	C _{rss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	95	-	
C _{rss} /C _{iss} ratio			-	0.050	0.100	
	_	V _{DS} = 20 V, V _{GS} = 10 V, I _D = 16 A	-	31.4	48	
Total gate charge	Q_g	20 - 7 00 - 7 0	-	14.2	22	nC
Gate-source charge	Q _{as}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 16 \text{ A}$	-	6.7	-	
Gate-drain charge	Q _{qd}	50 =- 1, 1d0 1,	-	5.1	-	
Output charge	Q _{oss}	V _{DS} = 20 V, V _{GS} = 0 V	-	7.1	-	
Gate resistance	R _q	f = 1 MHz	0.2	1.1	2.2	Ω
Turn-on delay time	t _{d(on)}		-	10	20	
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_1 = 2 \Omega$	-	5	10	
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	25	50	
Fall time	t _f		-	5	10	
Turn-on delay time	t _{d(on)}		-	25	50	ns
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$	-	45	90	
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	22	45	
Fall time	t _f		-	7	15	
Drain-Source Body Diode Characteristic						I.
Continuous source-drain diode current	Is	T _C = 25 °C -	-	-	52	А
Pulse diode forward current ($t_p = 100 \mu s$)	I _{SM}	-	-	-	100	
Body diode voltage	V _{SD}	I _S = 5 A	-	0.76	1.1	V
Body diode reverse recovery time	t _{rr}	<u> </u>	-	20	40	ns
Body diode reverse recovery charge	Q _{rr}	$I_F = 5 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	16	35	nC
Reverse recovery fall time	t _a	$T_{\rm J} = 25 ^{\circ}{\rm C}$	_	12	-	
Reverse recovery rise time	t _b		_	8	_	ns

Notes

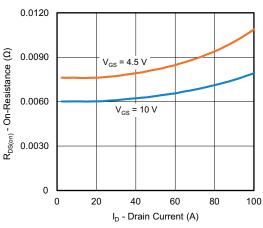
- a. Pulse test; pulse width $\leq 300~\mu\text{s},$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

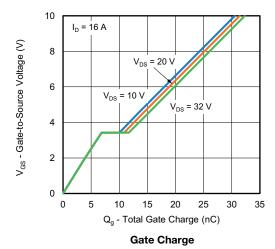


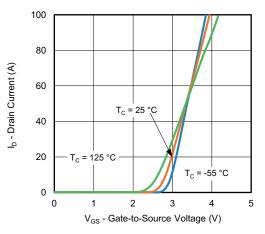


Output Characteristics

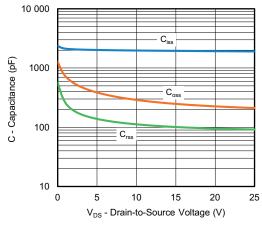


On-Resistance vs. Drain Current

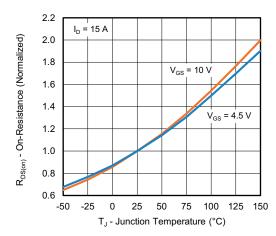




Transfer Characteristics

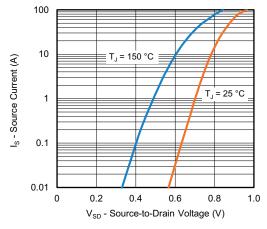


Capacitance

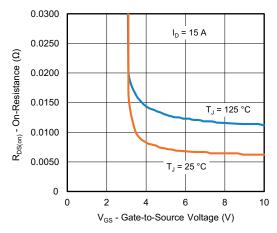


On-Resistance vs. Junction Temperature

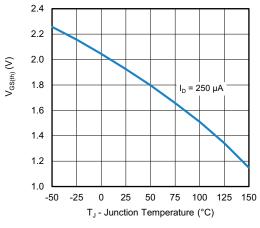




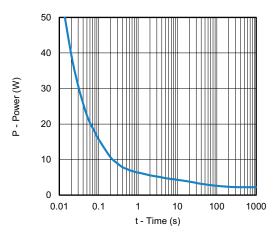
Source-Drain Diode Forward Voltage



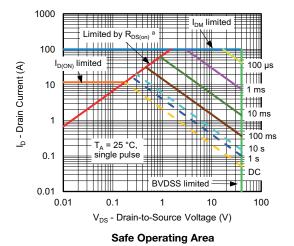
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



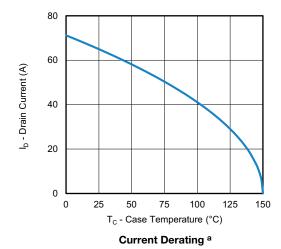
Single Pulse Power, Junction-to-Ambient

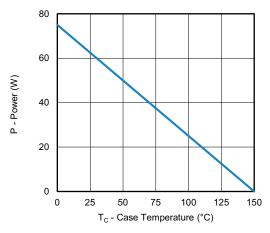


Note

a. $V_{GS} > minimum V_{GS}$ at which $R_{DS(on)}$ is specified





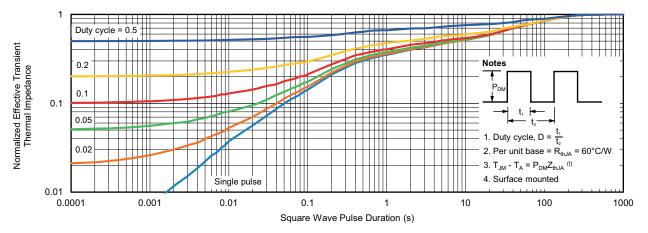


Power, Junction-to-Ambient

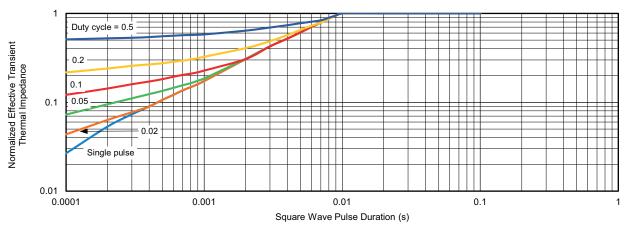
Note

b. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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